

RoHS Compliant

Features

- · Choice of various viewing angles
- · Available on tape and reel
- Reliable and robust
- · Lead Free

Applications

- TV set
- Monitor
- Telephone
- Computer

Selection Guide

Part Number	Dice	Lens Type	Luminous intensity(mcd) @ 20mA		
			Min	Тур	Max
MP008266	(R)AlGaInP	White Diffused	400	1000	-
	(B)InGaN		900	500	-
	(G)InGaN		300	1700	-

Note: 1.1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical and Optical Characteristics

Parameter	Device	Min.	Тур	Max	Units	Test conditions
	R	1.7	2	2.4		
Forward voltage	G	2.7	3	3.6	V	IF=20mA
	В	2.7	3	3.6		
Reverse Current	IR	-	-	10	uA	VR=5V
	R	618	-	630		
Dominant wavelength	G	510	-	520	nm	IF=20mA
	В	460	-	470		

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Units
	R	60	
Power Dissipation	G	90	mW
	В	90	
DC Forward Current	IF	30	mA
Peak Forward Current [1]	IFP	60	
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	2000	V
Operating Temperature	Topr	-40 to +85	°C
Storage Temperature	Tstg	-40 to +100	
Lead Soldering Temperature [1.6mm(.063") From Body]		260°C for 5 seconds	

Notes: 1. 1/10 Duty cycle,0.1ms pulse width.

2. Measurement Errors:Forward Voltage:±0.1V,Luminous Intensity:±10%mcd,Wavelength(x,y)±1nm/±0.01

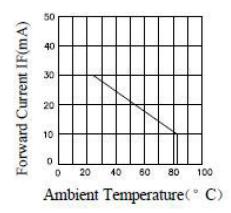


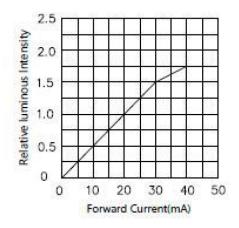
^{2.} The above luminous intensity measurement allowance tolerance ±15%

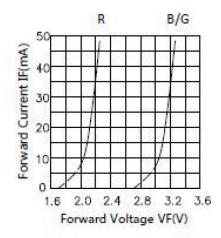


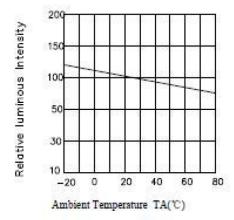
Typical optical characteristics curves

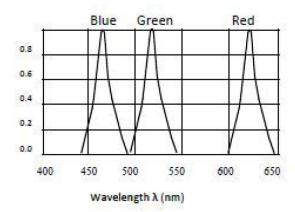
Ambient Temperature VS. Forward Current

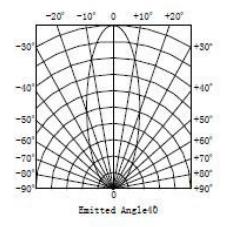








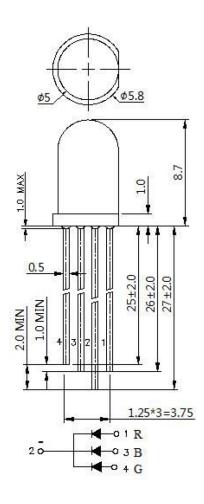








Dimensions



Tolerance is ±0.25mm unless otherwise noted.

Dimensions: Millimetres

1.Soldering

- · When soldering leave a minimum of 2mm clearance from the base of the lens to the soldering point.
- · Dipping the lens into the solder must be avoided.
- Do not apply any external stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering conditions:

Solder	ing iron	Wave soldering		
Temperature	320°C Max	Pre-heat Pre-heat time	120°C Max 120 sec.Max	
Soldering time	3 sec.Max (one time only)	Solder wave Soldering time	260°C Max 5 sec.Max	

Note: Excessive soldering temperature and/or time might result in deformation of the LED lens or catastrophic failure of the LED.



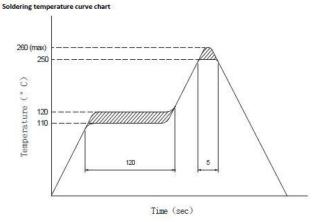


4. Drive Method

An LED is a current-operated device, In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.



- (A) Recommended circuit
- (B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.



NOTES

After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature. A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

Part Number Table

Description	Part Number
Round LED, Red/Geen/Blue, 630/520/470nm, 1000/1700/500mcd, Through hole	MP008266

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